## **EE-SY1200**

### **Photomicrosensor (Reflective)**

#### ■ Dimensions

Terminal No.

Κ

С

Ε

Name

Anode

Cathode

Collector

Emitter

Note

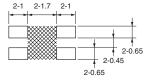
Unless otherwise specified tolerances are ±0.15.

No burrs dimensions are included in outline dimensions.

(Unit: mm)

The burrs dimensions are 0.15 MAX. Diagonal line indicate the region is part Au plating area.

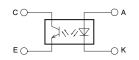
#### **Recommended Soldering Pattern**



Note 1. The shaded portion in the above figure may cause shorting. Do not wire in this portion.

 The dimensional tolerance for the recommended soldering pattern is ±0.1 mm.

#### **Internal Circuit**



#### ■ Features

- Ultra-compact model.
- PCB surface mounting type.
- High S/N ratio
   (High light current / Low leakage current)

## ■ Absolute Maximum Ratings (Ta=25°C)

	Item	Symbol	Rated value	Unit
	Forward current	lF	50*1	mA
Emitter	Pulse forward current	IFP	500* <sup>2</sup>	mA
	Reverse voltage	VR	4	V
Detector	Collector-Emitter voltage	VCEO	30	٧
	Emitter-Collector voltage	VECO	5	٧
	Collector current	Ic	20	mA
	Collector dissipa- tion	Pc	50*1	mW
Operating temperature		Topr	-25 to +85	°C
Storage temperature		Tstg	-40 to +100	°C
Reflow so	Idering temperature	Tsol	240*3	°C

- Refer to the temperature rating chart if the ambient temperature exceeds 25°C.
- \*2. The pulse width is 10 μs maximum with a frequency of
- \*3. Complete soldering within 10 seconds for reflow soldering.

#### **■** Electrical and Optical Characteristics (Ta=25°C)

		Value						
Item		Symbol	MIN.	TYP.	MAX.	Unit	Condition	
Emitter	Forward voltage	VF		1.2	1.4	V	I <sub>F</sub> = 20 mA	
	Reverse current	IR			10	μА	VR = 4 V	
	Peak emission wave- length	λь		940		nm		
Detector	Light current 1	I <sub>L</sub> 1	200		1000	μА	I <sub>F</sub> = 10 mA, V <sub>CE</sub> = 2 V, Aluminum- deposited surface, d = 4 mm* <sup>1</sup>	
	Light current 2	I L2	150			μА	IF = 4 mA, VcE = 2 V, Aluminum-deposited surface, d = 1 mm*1	
	Dark current	ΙD		2	200	nA	VCE = 10 V, 0 ℓx	
	Leakage current 1	I LEAK1			500	nA	IF = 10 mA, VcE = 2 V, with no reflection*2	
	Leakage current 2	I LEAK2			200	nA	IF = 4 mA, VcE = 2 V, with no reflection*2	
	Collector-Emitter saturated voltage	Vce (sat)				V		
	Peak spectral sensitivity wavelength	λР		850		nm		
Rising time		tr		30		μs	$Vcc = 2 V, R_L = 1 kΩ,$ $I_L = 100 μA, d = 1 mm^{*1}$	
Falling time		tf		30		μs	Vcc = 2 V, RL = 1 kΩ, $IL = 100 μA, d = 1 mm^{*1}$	

<sup>\*1.</sup> The letter "d" indicates the distance between the top surface of the sensor and the sensing object.

<sup>\*2.</sup> Depends on the installed condition of the Photomicrosensor, the detector may receive the sensor's LED light and/or the external light which is reflected from surroundings of the Photomicrosensor and /or the background object.

Please confirm the condition of the Photomicrosensor by actual intended application prior to the mass production use.

**EE-SY1200 OMRON** 

Fig 2. Forward Current vs. Forward Voltage

#### ■ Engineering Data

Fig 1. Forward Current vs. Collector **Dissipation Temperature Rating** 

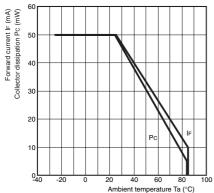


Fig 4. Light Current vs. Collector-Emitter Voltage Characteristics (Typical)

IF=15mA, d=4m

JF=10mA, d=4n IF=4mA, d=1mn

Collector-Emitter voltage VcE (V)

Load resistance RL (kΩ)

Fig 7. Response Time vs. Load Resistance Characteristics (Typical)

1,400

ਰੋ 1,20i 1,000

800

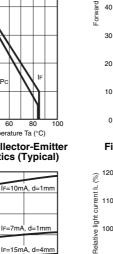
400

20

(E) 10,000

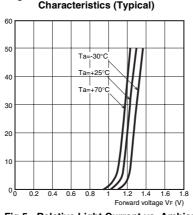
1,00

Response time tr,tf



(mA)

Fig 5. Relative Light Current vs. Ambient Temperature Characteristics (Typical)



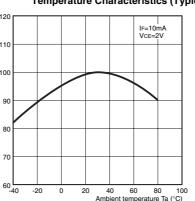


Fig 8. Sensing Distance Characteristics (Typical)

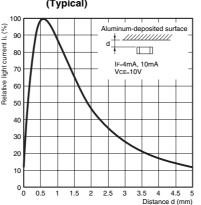


Fig 11. Response Time Measurement Circuit

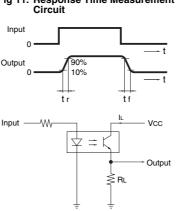


Fig 3. Light Current vs. Forward Current Characteristics (Typical)

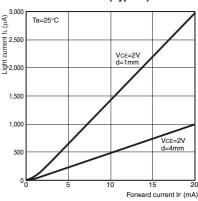


Fig 6. Dark Current vs. Ambient Temperature Characteristics (Typical)

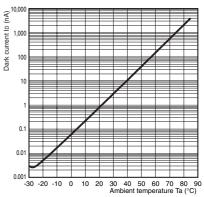


Fig 9. Sensing Position Characteristics (Typical)

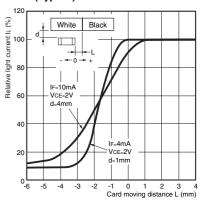


Fig 12. Light Current Measurement Setup Diagram

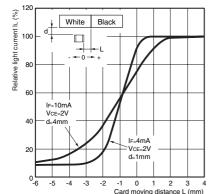
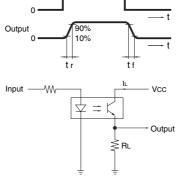
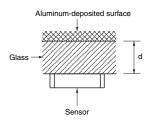


Fig 10. Sensing Position Characteristics

(Typical)

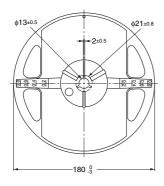




#### **EE-SY1200**

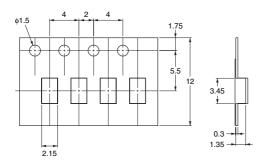
#### **■** Tape and Reel

#### ■ Reel Dimension (Unit: mm)



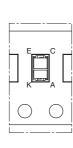


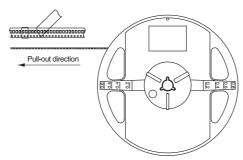
#### ■ Tape Dimension (Unit: mm)



#### Part Mounting Direction

• The devices are oriented in the rectangular holes in the carrier tape so that the edge with the LED faces the round feeding holes.





#### Tape Quantity

2,000 pcs./reel

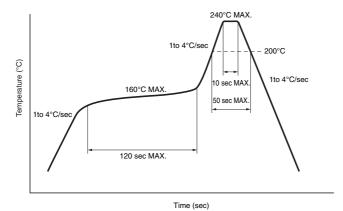
omron EE-SY1200

#### ■ Precautions to be taken on mounting

#### Temperature Profile

The reflow soldering can be implemented in two times complying with the following diagram.

All the temperatures in the product must be within the diagram.



#### Manual soldering

The manual soldering cannot be applied to the products.

There is a possibility that the housing is deformed and/or Au plating is peeled off by heat.

#### Other Notes

The use of infrared lamp causes the temperature at the resin to rise particularly too high.

All the temperatures in the product must be within the above diagram.

Do not immerse the resin part into the solder.

Even if within the above temperature diagram, there is a possibility that the gold wire in the products is broken in case that the deformation of PCB gives the stress to the product terminals.

Please confirm the conditions of the reflow soldering fully by actual solder reflow machine prior to the mass production use.

#### ■ Storage and Handling after Opening

#### Storage Conditions

In order to avoid the absorption of moisture, the products shall be stored in a dry box with desiccant or in the following conditions.

Storage temp. : 5 to 30°C Storage humidity : 70%RH or less

#### Treatment after Opening

- 1. Reflow soldering must be done within 48 hours stored at the conditions of humidity 60%RH or less and temperature 5 to 25°C.
- 2. In case of long time storage after open, please mount at the conditions of humidity 70%RH or less and temperature 5 to 30°C within 1 week by using dry box or resealing with desiccant in moisture-proof bag by sealer.

#### Baking before Mounting

In case that it could not carry out the above treatment, it is able to mount by baking treatment. However baking treatment shall be limited only 1 time.

Recommended conditions: 60°C, 12 to 24 hours (reeled one)
100°C, 8 to 24 hours (loose one)

# AMEYA360 Components Supply Platform

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